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Kind regards,

Team Nexperia



2PB709ART

45 V, 100 mA PNP general-purpose transistor

Rev. 01 — 19 March 2007

Product data sheet

1. Product profile

1.1 General description

PNP general-purpose transistor in a small SOT23 (TO-236AB) Surface-Mounted Device (SMD) plastic package.

NPN complement: 2PD601ART.

1.2 Features

- General-purpose transistor
- Small SMD plastic package

1.3 Applications

- General-purpose switching and amplification

1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CE0}	collector-emitter voltage	open base	-	-	-45	V
I_C	collector current		-	-	-100	mA
h_{FE}	DC current gain	$V_{CE} = -10\text{ V};$ $I_C = -2\text{ mA}$	210	-	340	

2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Symbol
1	base		
2	emitter		
3	collector		

sym013

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
2PB709ART	-	plastic surface-mounted package; 3 leads	SOT23

4. Marking

Table 4. Marking codes

Type number	Marking code ^[1]
2PB709ART	C5*

- [1] * = -: made in Hong Kong
 * = p: made in Hong Kong
 * = t: made in Malaysia
 * = W: made in China

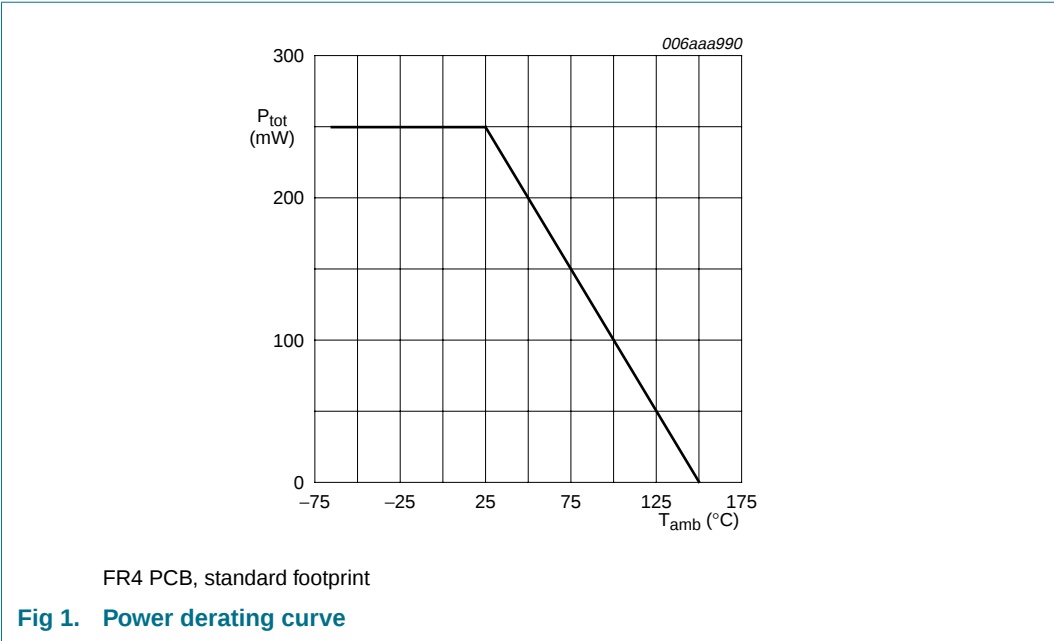
5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CBO}	collector-base voltage	open emitter	-	-45	V
V_{CEO}	collector-emitter voltage	open base	-	-45	V
V_{EBO}	emitter-base voltage	open collector	-	-6	V
I_C	collector current		-	-100	mA
I_{CM}	peak collector current	single pulse; $t_p \leq 1$ ms	-	-200	mA
I_{BM}	peak base current	single pulse; $t_p \leq 1$ ms	-	-100	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C	^[1] -	250	mW
T_j	junction temperature		-	150	°C
T_{amb}	ambient temperature		-65	+150	°C
T_{stg}	storage temperature		-65	+150	°C

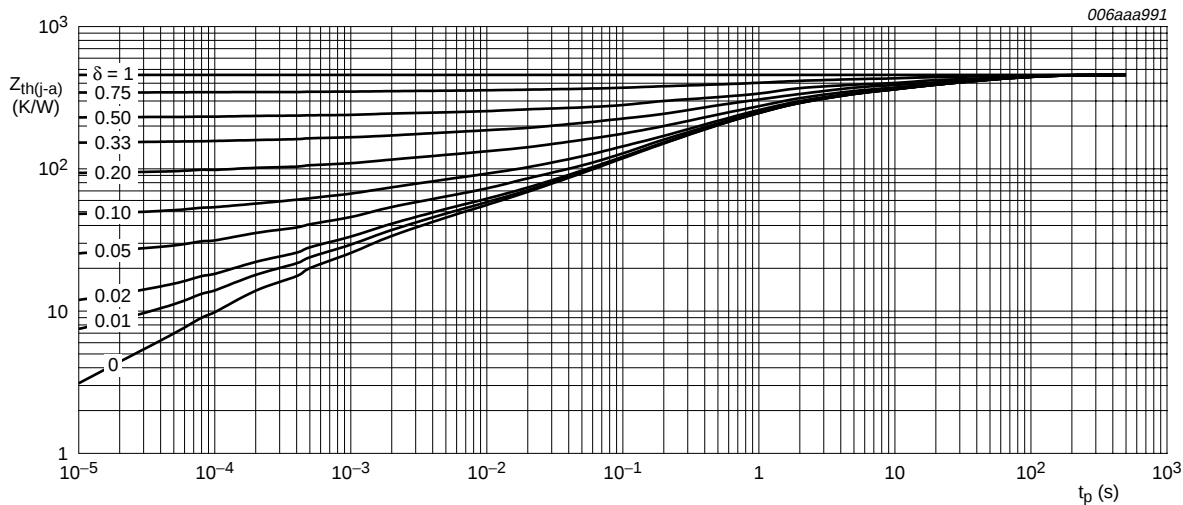
- [1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.



6. Thermal characteristics

Table 6. Thermal characteristics						
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] -	-	500	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		-	-	140	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.



FR4 PCB, standard footprint

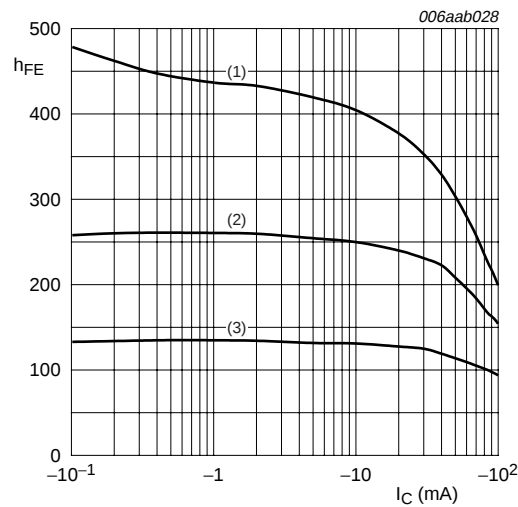
Fig 2. Transient thermal impedance from junction to ambient as a function of pulse duration for SOT23 (TO-236AB); typical values

7. Characteristics

Table 7. Characteristics
T_{amb} = 25 °C unless otherwise specified.

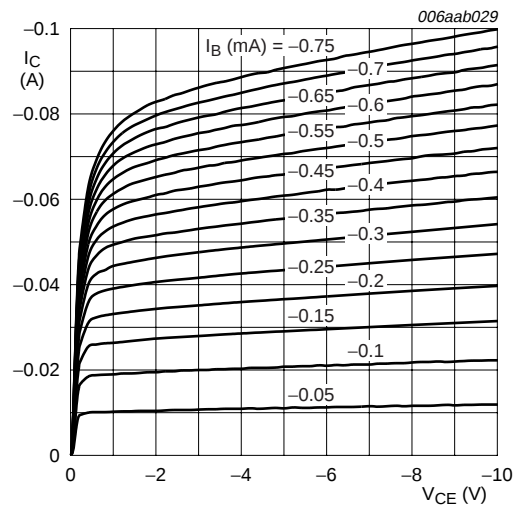
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I _{CBO}	collector-base cut-off current	V _{CB} = −45 V; I _E = 0 A	-	-	−10	nA
		V _{CB} = −45 V; I _E = 0 A; T _j = 150 °C	-	-	−5	μA
I _{EBO}	emitter-base cut-off current	V _{EB} = −5 V; I _C = 0 A	-	-	−10	nA
h _{FE}	DC current gain	V _{CE} = −10 V; I _C = −2 mA	210	-	340	
V _{CEsat}	collector-emitter saturation voltage	I _C = −100 mA; I _B = −10 mA	[1]	-	−500	mV
f _T	transition frequency	V _{CE} = −10 V; I _C = −1 mA; f = 100 MHz	70	-	-	MHz
C _c	collector capacitance	V _{CB} = −10 V; I _E = I _E = 0 A; f = 1 MHz	-	-	5	pF

[1] Pulse test: t_p ≤ 300 μs; δ ≤ 0.02.



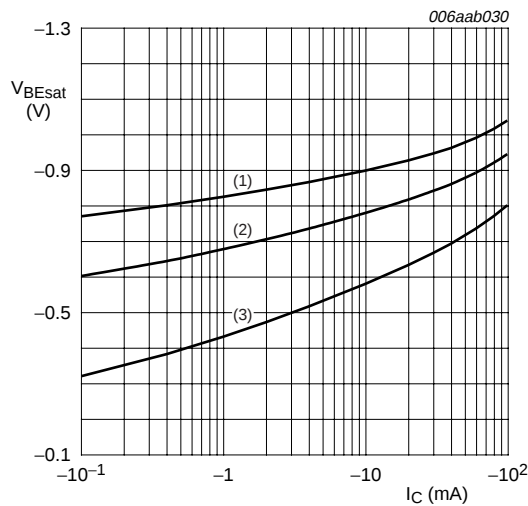
- $V_{CE} = -10\text{ V}$
(1) $T_{amb} = 150\text{ }^{\circ}\text{C}$
(2) $T_{amb} = 25\text{ }^{\circ}\text{C}$
(3) $T_{amb} = -55\text{ }^{\circ}\text{C}$

Fig 3. DC current gain as a function of collector current; typical values



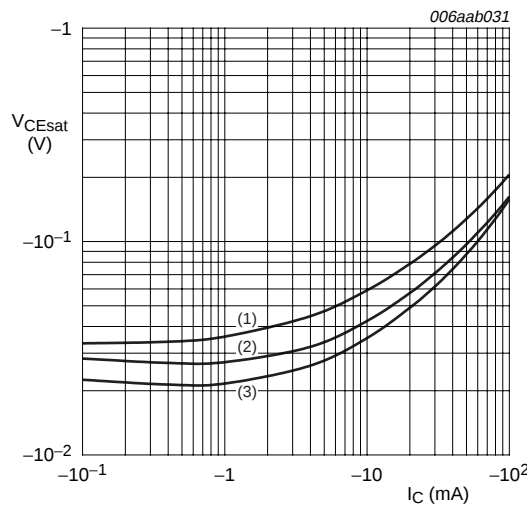
$T_{amb} = 25\text{ }^{\circ}\text{C}$

Fig 4. Collector current as a function of collector-emitter voltage; typical values



- $I_C/I_B = 10$
(1) $T_{amb} = -55\text{ }^{\circ}\text{C}$
(2) $T_{amb} = 25\text{ }^{\circ}\text{C}$
(3) $T_{amb} = 150\text{ }^{\circ}\text{C}$

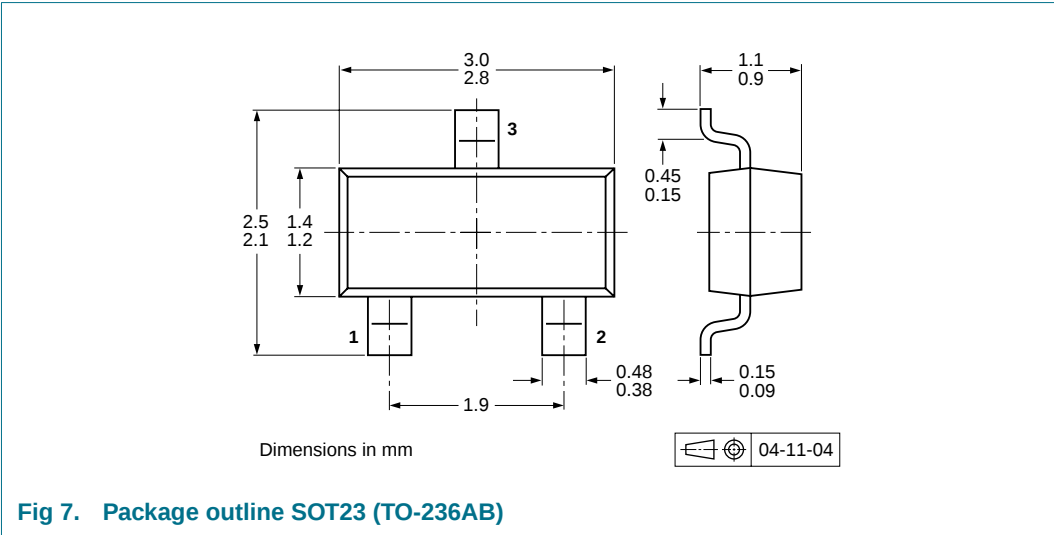
Fig 5. Base-emitter saturation voltage as a function of collector current; typical values



- $I_C/I_B = 10$
(1) $T_{amb} = 150\text{ }^{\circ}\text{C}$
(2) $T_{amb} = 25\text{ }^{\circ}\text{C}$
(3) $T_{amb} = -55\text{ }^{\circ}\text{C}$

Fig 6. Collector-emitter saturation voltage as a function of collector current; typical values

8. Package outline



9. Packing information

Table 8. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.^[1]

Type number	Package	Description	Packing quantity	
			3000	10000
2PB709ART	SOT23	4 mm pitch, 8 mm tape and reel	-215	-235

[1] For further information and the availability of packing methods, see [Section 13](#).

10. Soldering

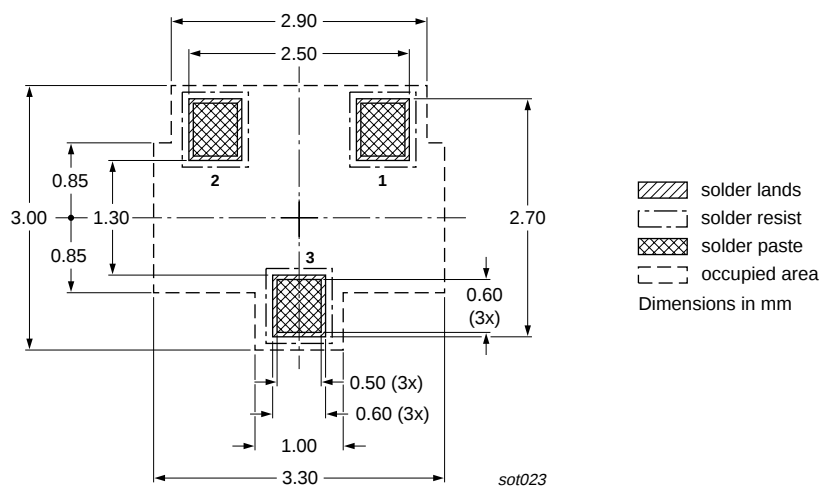


Fig 8. Reflow soldering footprint SOT23 (TO-236AB)

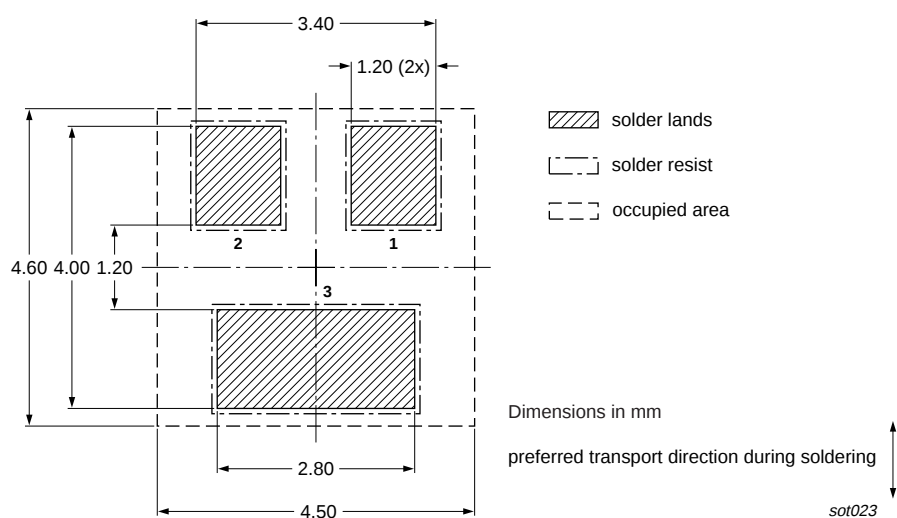


Fig 9. Wave soldering footprint SOT23 (TO-236AB)

11. Revision history

Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
2PB709ART_1	20070319	Product data sheet	-	-

12. Legal information

12.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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